

Product Summary

V _{RRM} (V)	I _o (mA)	V _F Max (V) @ +25°C	I _R Max (μA) @ +25°C
30	200	0.50	9

Description

The SDM02U30CSP is a 30-Volt 0.2A Schottky Barrier Diode that is optimized for low forward voltage drop and low leakage current. It's housed in a compact Chip Scale Package (CSP) that occupies only 0.18mm² board space. The low thermal resistance enables designers to meet design challenges of increasing efficiency while reducing board space. It is ideally suited for use in portable applications.

Applications

- Blocking Diode
- Reverse Protection Diode
- Boost Diode

Features and Benefits

- 0.18mm² Footprint, Off Board Profile of 0.28mm
- Low Forward Voltage of 0.50V (Max) – Minimizes Power Dissipation Losses
- Low Leakage – Maximizes Battery Power
- Soft, Fast Switching Capability
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

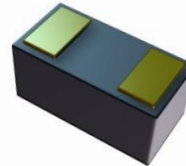
Mechanical Data

- Case: X3-WLB0603-2
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity Indicator: Cathode Dot
- Terminals: NiAu Bump. Solderable per MIL-STD-202, Method 208 ^(a)
- Weight: 0.1mg (Approximate)

X3-WLB0603-2



Top View



Bottom View

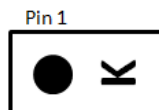
Ordering Information (Note 4)

Part Number	Case	Packaging
SDM02U30CSP-7	X3-WLB0603-2	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

X3-WLB0603-2



K = Product Type Marking Code
Dot Denotes Cathode Pin

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Average Rectified Output Current	I _O	0.2	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	4.5	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	215	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V _F	—	0.24	0.29	V	I _F = 1mA, T _J = +25°C
		—	0.30	0.34		I _F = 10mA, T _J = +25°C
		—	0.40	0.46		I _F = 100mA, T _J = +25°C
		—	0.45	0.50		I _F = 200mA, T _J = +25°C
		—	0.39	—		I _F = 200mA, T _J = +125°C
Leakage Current (Note 6)	I _R	—	0.4	2.0	μA	V _R = 10V, T _J = +25°C
		—	1.5	9	μA	V _R = 30V, T _J = +25°C
		—	0.7	—	mA	V _R = 30V, T _J = +125°C
Junction Capacitance	C _T	—	7	—	pF	V _R = 10V, T _J = +25°C, f = 1MHz

Notes: 5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout per <http://www.diodes.com/package-outlines.html>.
6. Short duration pulse test used to minimize self-heating effect.

Typical Electrical Characteristics

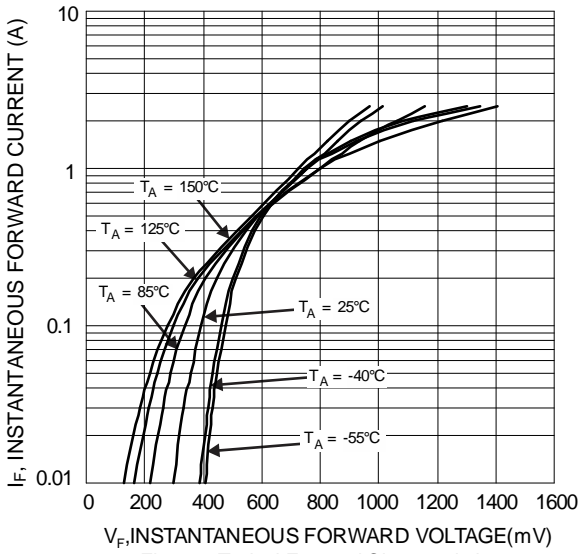


Figure 1 Typical Forward Characteristics

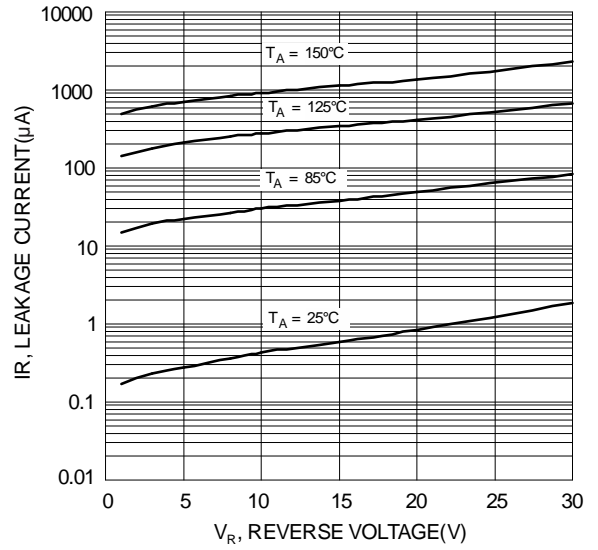


Figure 2 Typical Reverse Characteristics

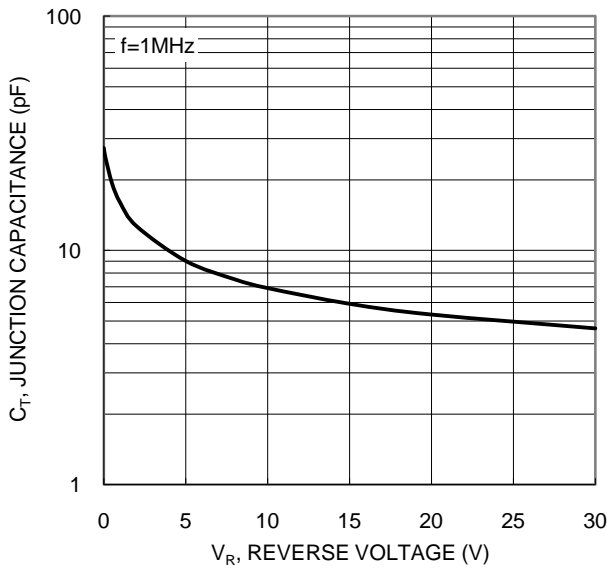


Figure 3. Typical Junction Capacitance

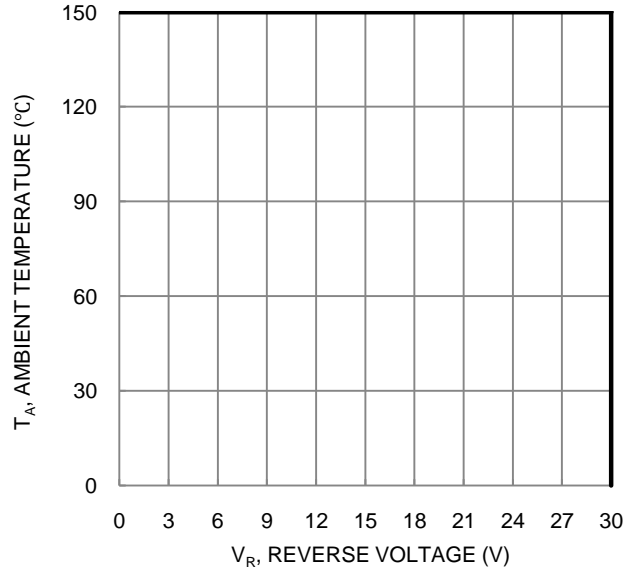
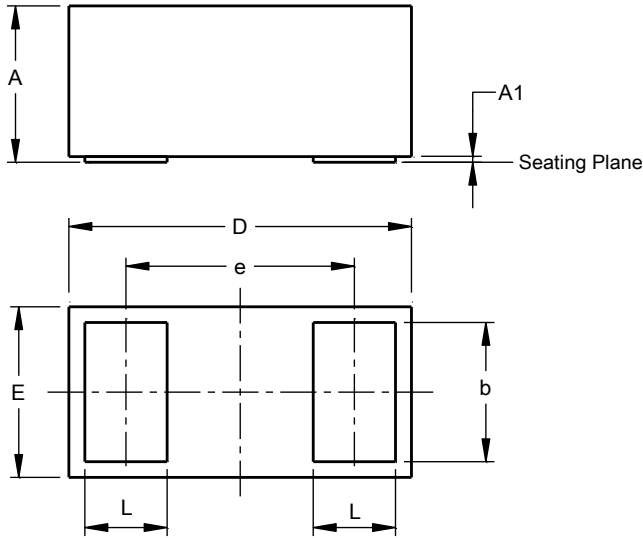


Figure 4. Operating Temperature Derating

Package Outline Dimensions (Note 7)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X3-WLB0603-2



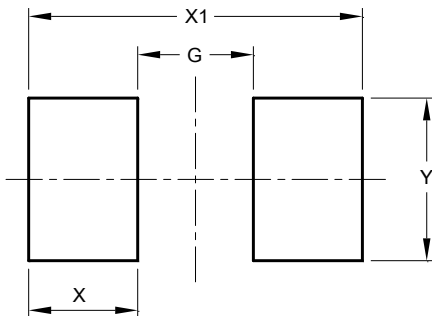
X3-WLB0603-2			
Dim	Min	Max	Typ
A	0.250	0.300	0.275
A1	0.00	0.01	—
b	0.220	0.280	0.245
D	0.575	0.625	0.600
E	0.275	0.325	0.300
e	—	—	0.400
L	0.120	0.180	0.144
All Dimensions in mm			

Note 7: Device side walls are electrically active bare silicon. Avoid contact of solder or flux on the side walls during the PCB assembly process.

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X3-WLB0603-2



Dimensions	Value (in mm)
G	0.206
X	0.194
Y	0.291
X1	0.594

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